



**Ridgetop Group** INC  
ENGINEERING INNOVATION

# **The Odds of Test and Measurement**

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**Ridgetop Europe**

# Setting the Scene

- Electronic System :
  - “Assembly of the individual **components** and the **interconnection** between these components”
- Components:
  - Each component may consist of sub-components and interconnects

*?? How do we test and qualify interconnects ??*

# Challenges

- Interconnect quality and reliability assurance
  - 2.5/3D integration
  - Package qualifications
  - Device to board
  - Wires & cables
- Die crack detection
- Contact quality
  - Degraded – intermittent – permanent failure
- Life-time monitoring

# Interconnect Failure

- Interconnects are subject to
  - Manufacturing defects
  - Aging effects (electromigration)
  - Stress (thermal, electrical, chemical, mechanical, vibration)
- Detection can be
  - Easy – opens/shorts
  - Cumbersome – degradation/intermittencies

# Interconnect Integrity

- Validating whether the connection is good or bad
- Good Connection:
  - Low resistance (typ.  $< 1 \Omega$ )
  - No Disruption on data
- Bad Connection:
  - From resistive to Open – very high resistance (typ.  $> 1M\Omega$ )
  - Short
    - Short to ground (stuck-at 0 - s@0)
    - Short to supply (stuck-at 1 – S@1)
    - Short to other signal line
  - Intermittent
    - Temporarily open
    - Temporarily short

# Interconnect Reliability

- Validating whether the connection *remains* good over time
  - Check for degradation
  - Check for intermittencies
- Requires observation over time
  - Continuous observation
  - Observation at discrete time points.

# Intermittent Faults

- According to Standards:
  - An interconnect **intermittent** fault is an event that causes the interconnect resistance to increase for a **predefined amount** and last for a **minimum time**.
  - Fault detection is linked to # of occurrences
  - Definition evolved:
    - From: R increase of **1KΩ** lasting at least **1μs**
      - JEDEC 22-B111
    - To: R increase of **200Ω** lasting at least **200ns**
  - Interconnect is classified as failing if subsequent to the occurrence of the first event, nine more events are detected that occur within a period of time T2 that is less than or equal to 10% of the time to the occurrence of the first event T1. ( $T2 \leq 0.1 * T1$ )
- Reality
  - A single intermittence can cause a system to fail
  - NTF/NFF – RTOK – CND issues

# Interconnect Verification Techniques

- X-Ray Laminography
- Analog Harmonic Test
- RF induction & Analog junction technique
- Boundary Scan
- Daisy chain of interconnects
  - Qualification only
  
- ***SJ BIST***



# What is SJ BIST?

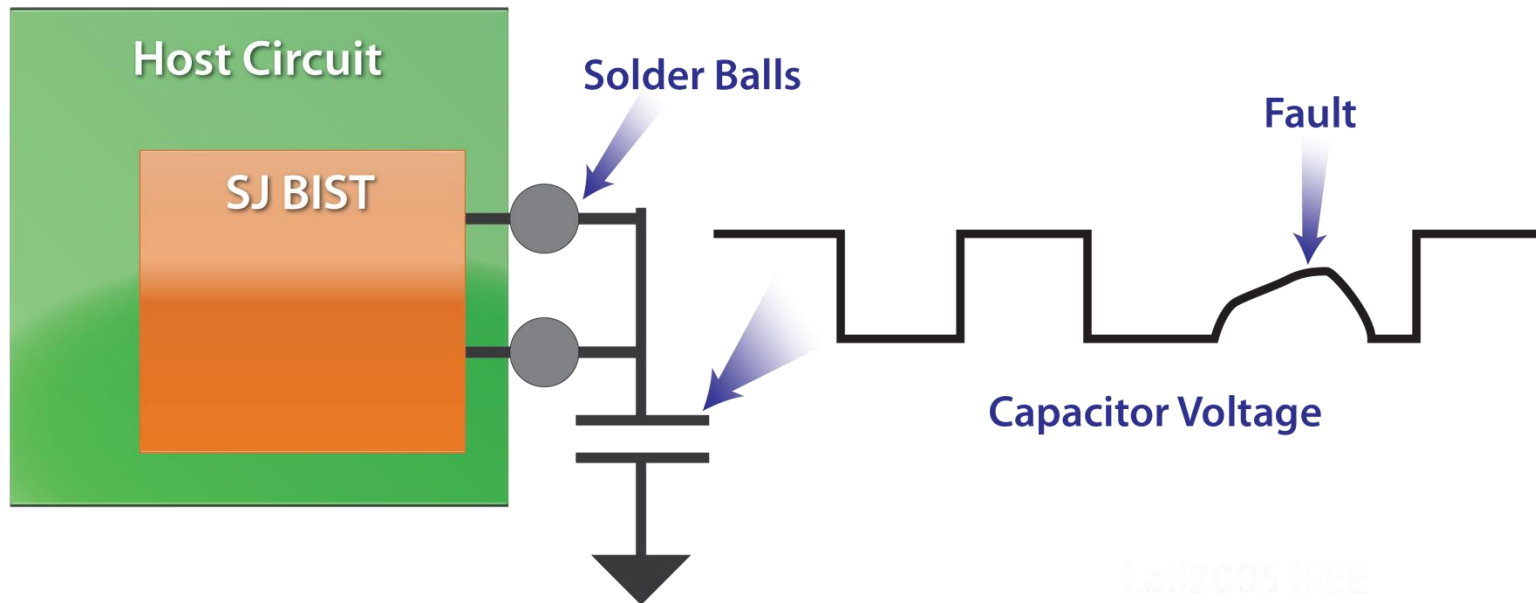
- SJ BIST = Solder Joint Built-in Self-Test
  - “Solder Joint”
    - Interconnection between Device & Board
    - Can be seen as reference to *any type of connection*
    - Originally developed for FPGA-BGA applications
  - “Built-in”
    - Part of a “host” circuit
  - “Self-Test”
    - Host circuit can test itself.

# What is SJ-BIST?

- SJ BIST = Solder Joint Built-in Self-Test
  - Original solution, enabling:
    - interconnect verification
    - validation of interconnect reliability
    - (life-time) monitoring of interconnect reliability
    - detection of intermittences
    - interconnect process qualification
  - Can be applied to validate the integrity and reliability of *any type* of interconnect

# SJ BIST™ Operation

- Run Algorithm similar to a memory test: W0 – R0; W1 – R1
- Runs concurrently with host circuit
- Verilog/VHDL core (patent pending)
  - Each core tests two I/O pins
  - Pins are externally wired together
  - Uses interconnect resistance and capacitance

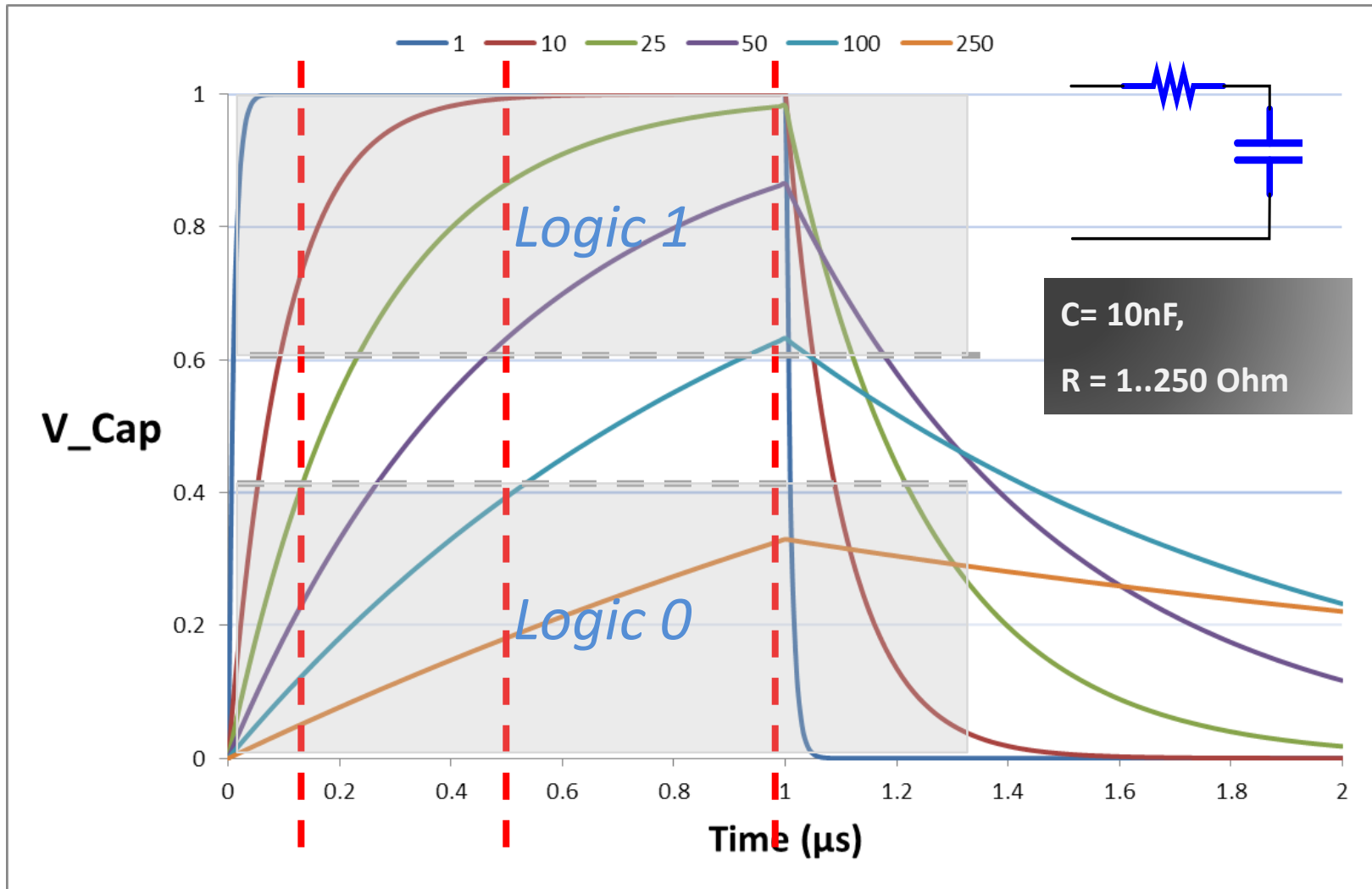


Lat2005 IEEE

# SJ BIST Concept

- Interconnect == Memory
  - Connection between two dedicated pins
- Storage element == Capacitance of interconnect
  - Intrinsic (parasitic) capacitance of wire
  - I/O input capacitance
  - Small add-on capacitance
- Test == Transfer Charge == Memory Test
  - Write 0's and 1's
  - Verify if 0's and 1's are correctly stored

# SJ BIST Concept



# SJ BIST Concept

- Major players:
  - 2 dedicated host pins
  - Interconnect between pins
  - Interconnect capacitance
    - intrinsic input capacitance + optional external cap
  - Interconnect resistance
    - low resistance == OK
    - increased resistance == Fault
  - Observation time
  - Continuous vs. scheduled test / observation

# SJ BIST Objectives & Features

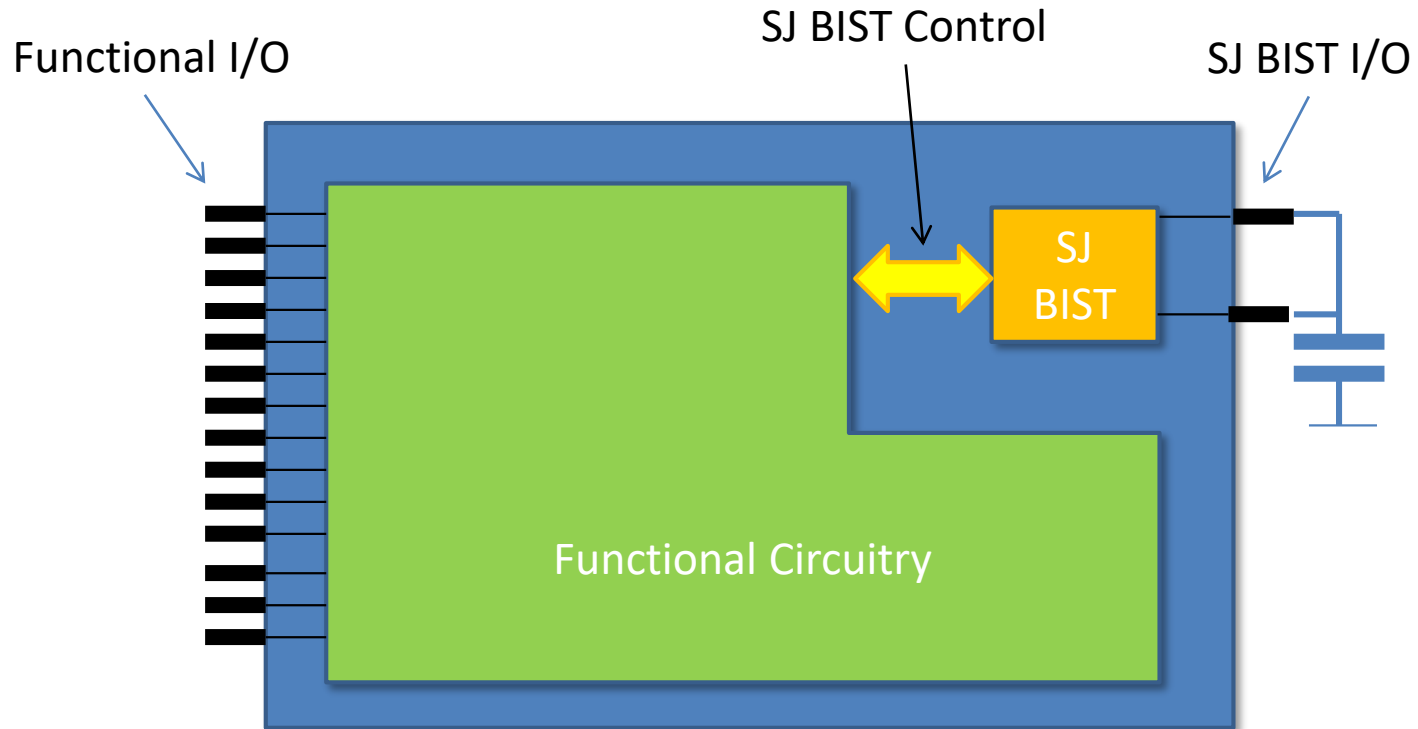
- Objectives
  - Detection of impending interconnect failures
  - Unique in-situ testing in operating circuits
  - Technology-independent
- Feature and Benefits
  - Detects solder fractures prior to catastrophic failure of circuit
  - Detects changes in interconnect resistance
  - Provides actionable maintenance data
  - Independently tested and verified
  - Endorsed by leading automotive and aerospace customers

# SJ BIST Operation

- Independent
  - Concurrent & Continuously
    - SJ BIST runs R/W tests as long as host circuit is powered on
    - SJ BIST flags specified events
    - Host inquires SJ BIST upon event or at specified time points
- Dependent
  - Host or Control unit enables SJ BIST at specific time points
  - SJ BIST runs for a specified amount of time
    - SJ BIST flags specified events
    - Host inquires SJ BIST

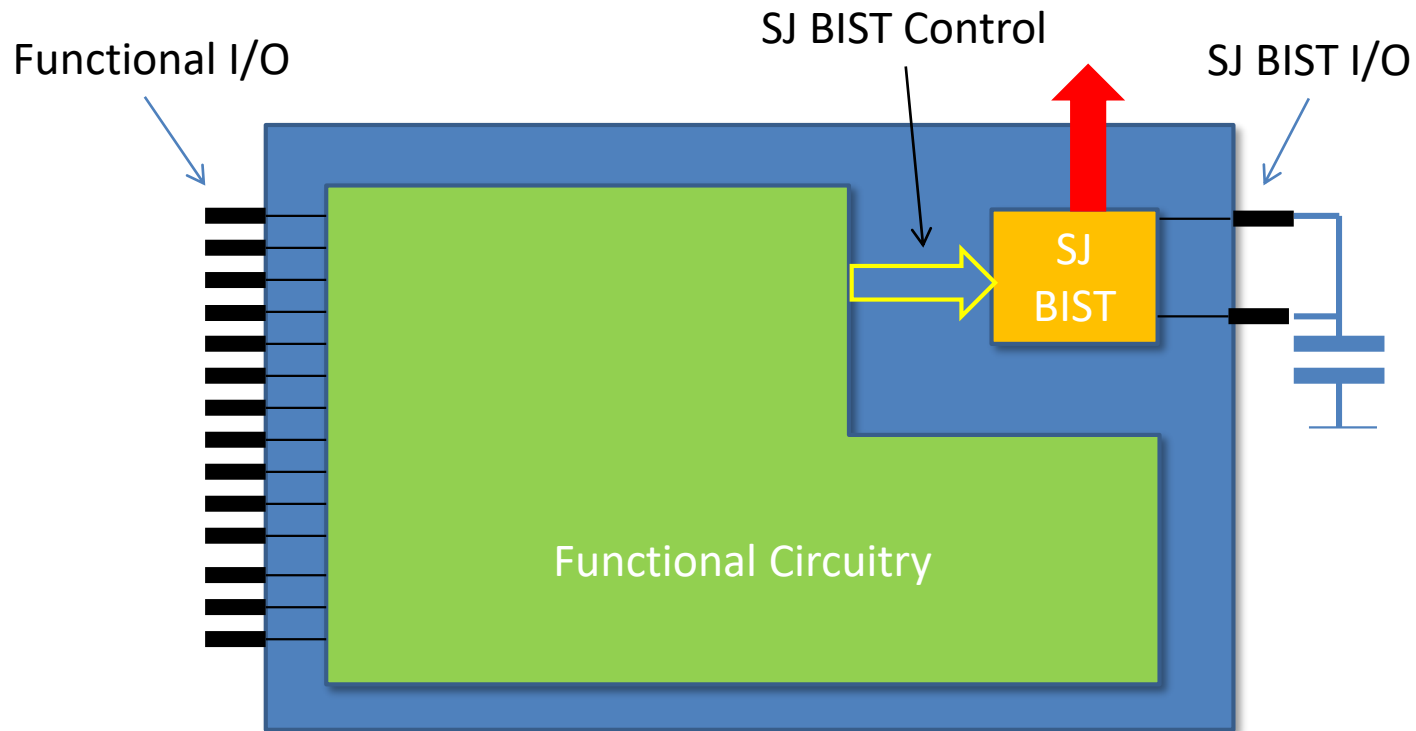


# SJ BIST Implementation



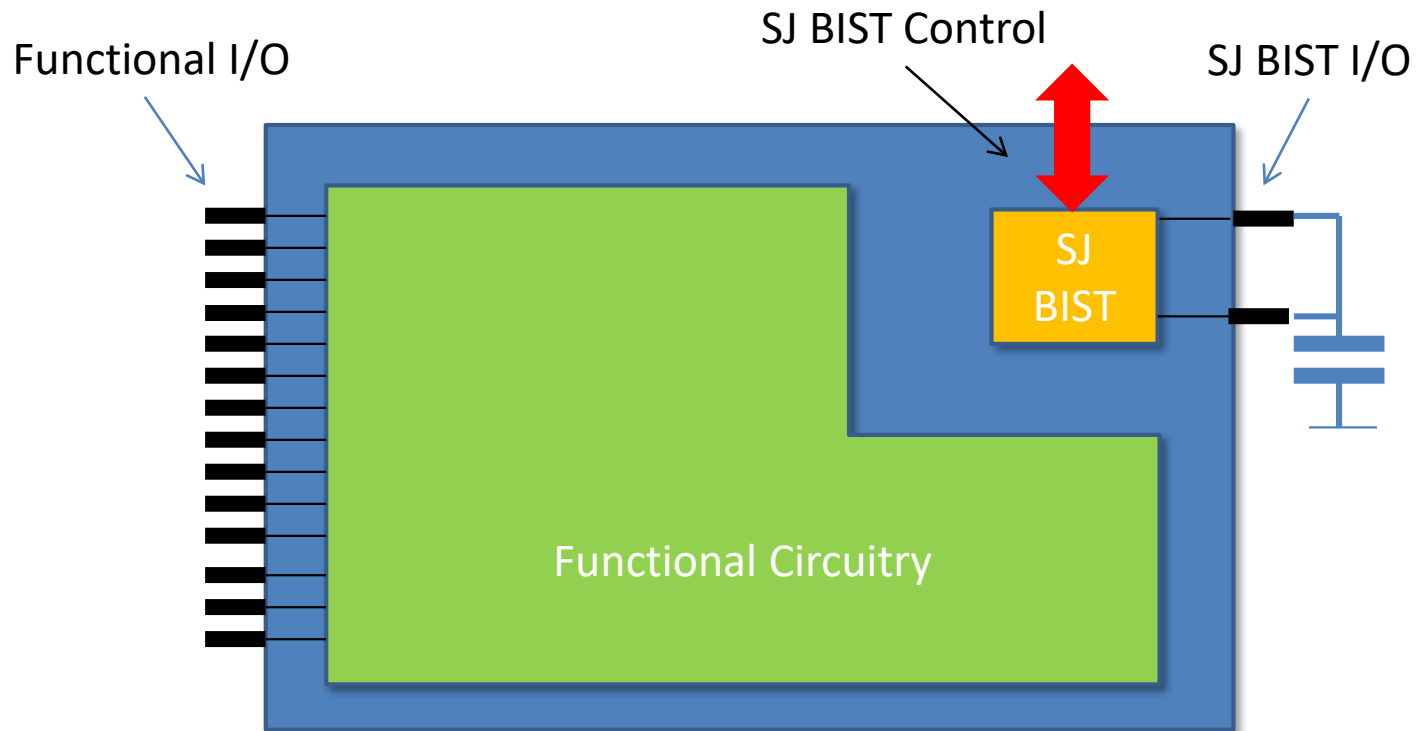
- SJ BIST runs concurrently with host circuit
- SJ BIST requires dedicated I/O

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- SJ BIST runs concurrently with host circuit
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# SJ BIST Information

- **Flags:**
  - Permanent vs Intermittent fault
  - Flags can be treated individually or combined in a global Pass/Fail flag
  - Provide “**occurrence**” information
- **Event Counts**
  - # of occurrences of a permanent or intermittent fault during a given timeframe
  - Provide “**severity**” information
- **Flags & Event counts are associated to each SJ BIST Test pin**

# SJ BIST & Detection of Failures

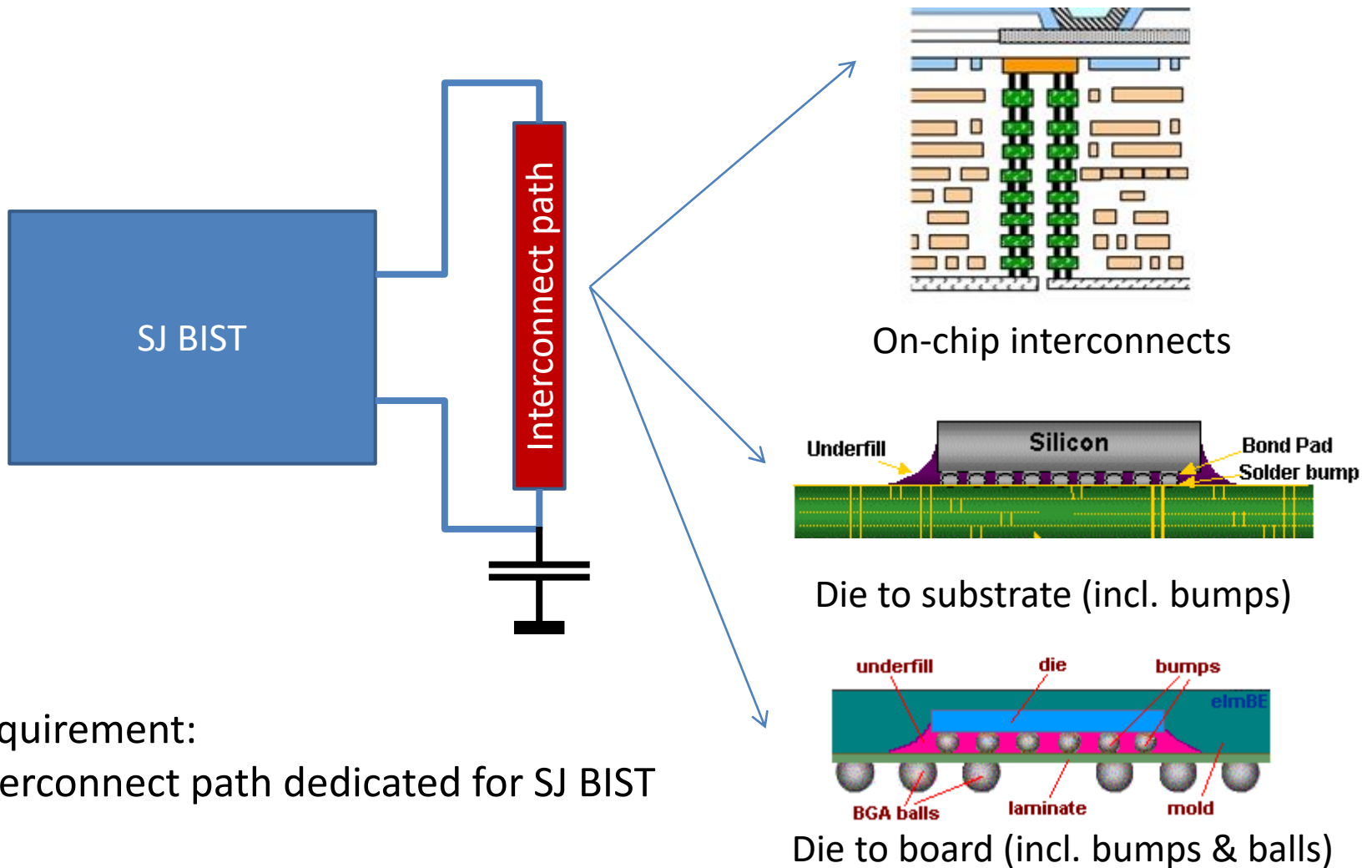
- Detection of **Intermittent** faults
  - SJ BIST can detect events that are lasting less than 10ns
  - SJ BIST can detect resistance increases of  $10\Omega$  or less
  - Detection is function of SJ BIST operating frequency, interconnect capacitance and interconnect resistance
- Fault detection is linked to SJ BIST configuration.

- Detection of **Degradation**
  - Interconnect degradation will result in permanent or intermittent fault introduction.
  - Test results will evolve from “good” to “fail”
  - If SJ BIST runs continuously a flag will be raised upon the occurrence of a fault
  - Failure time point (moment when the flag is raised) is function of SJ BIST configuration and hence tunable by the user.

# SJ BIST Applications

- Interconnect validation & monitoring
  - From on-chip interconnects to cable testing
- Assembly (solder) process qualification
  - From die stacking to system assembly
  - LT/ALT/HALT testing
- Package qualifications
- Die handling – Crack detection
- Assembly monitoring
  - In field testing
- Validation of packaging solutions & techniques
- ... and many more

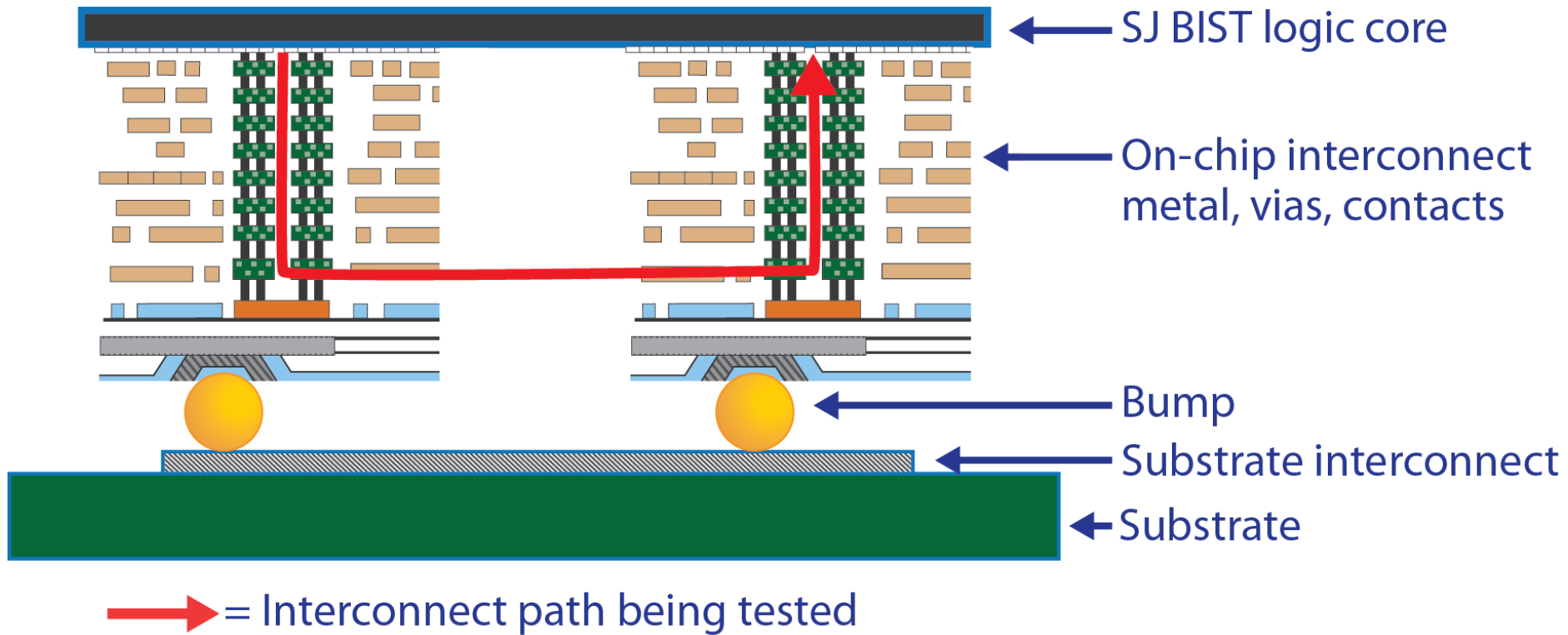
# SJ BIST Application





# SJ BIST Application

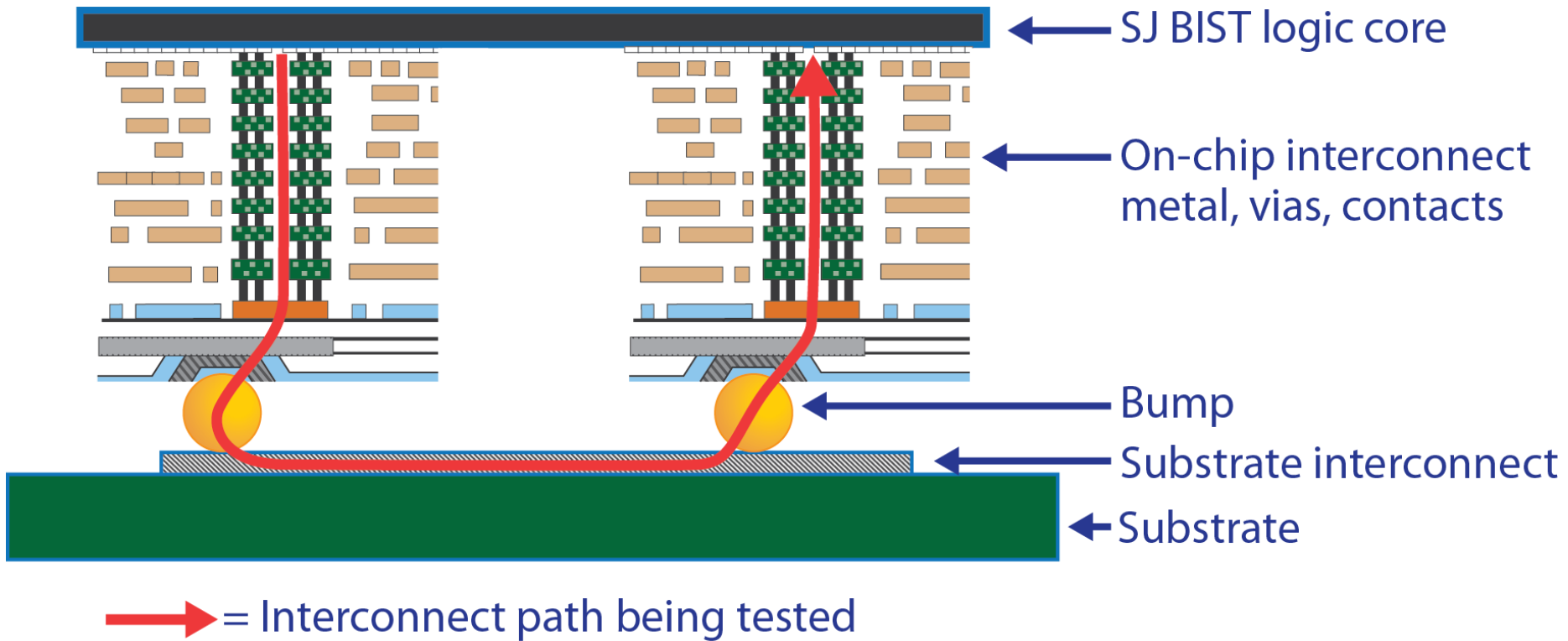
## Testing On-chip Interconnect



Need for dedicated on-chip path between SJ BIST™ Observation pins

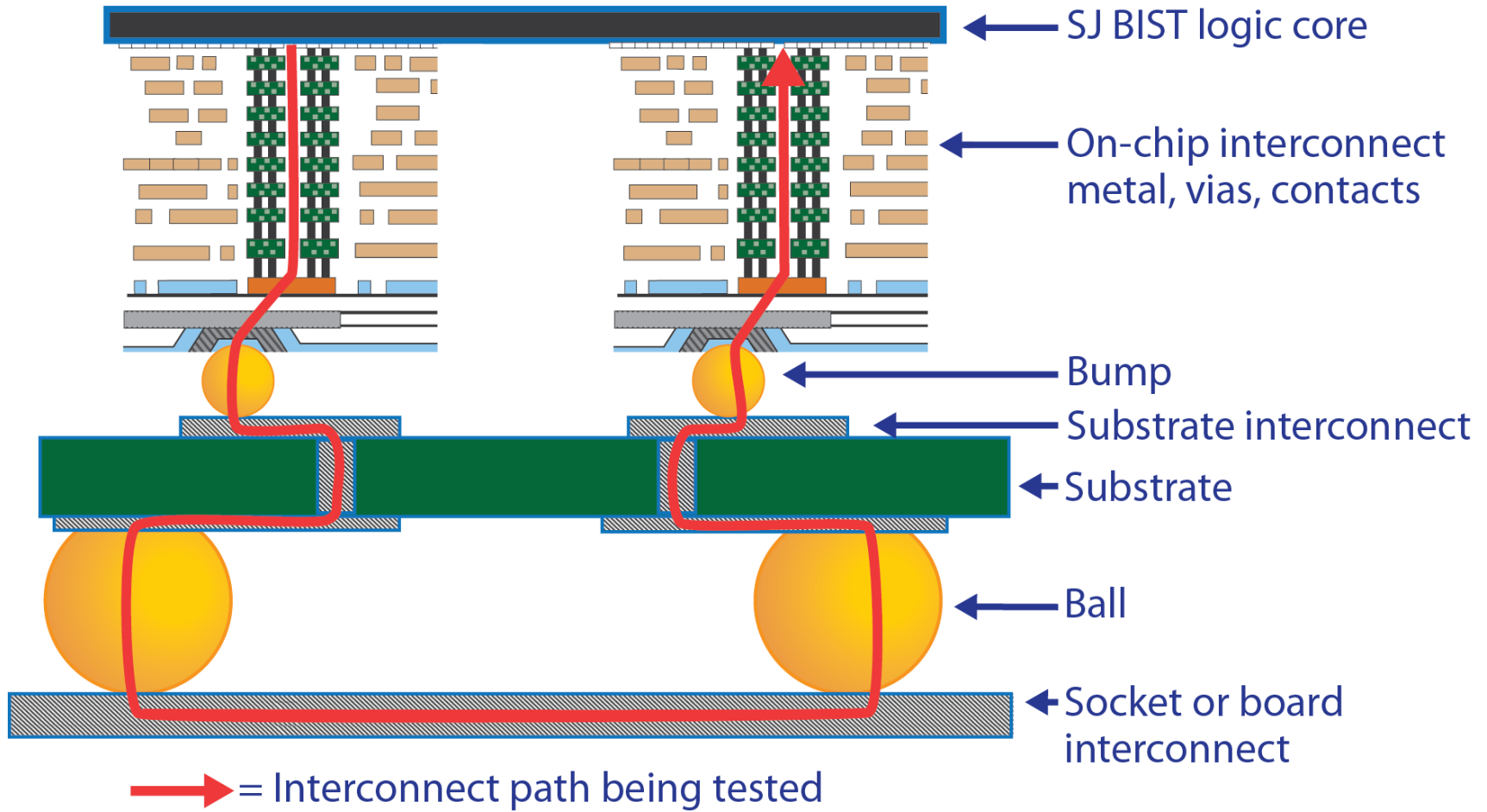
# SJ BIST Application

## Testing Die to Substrate



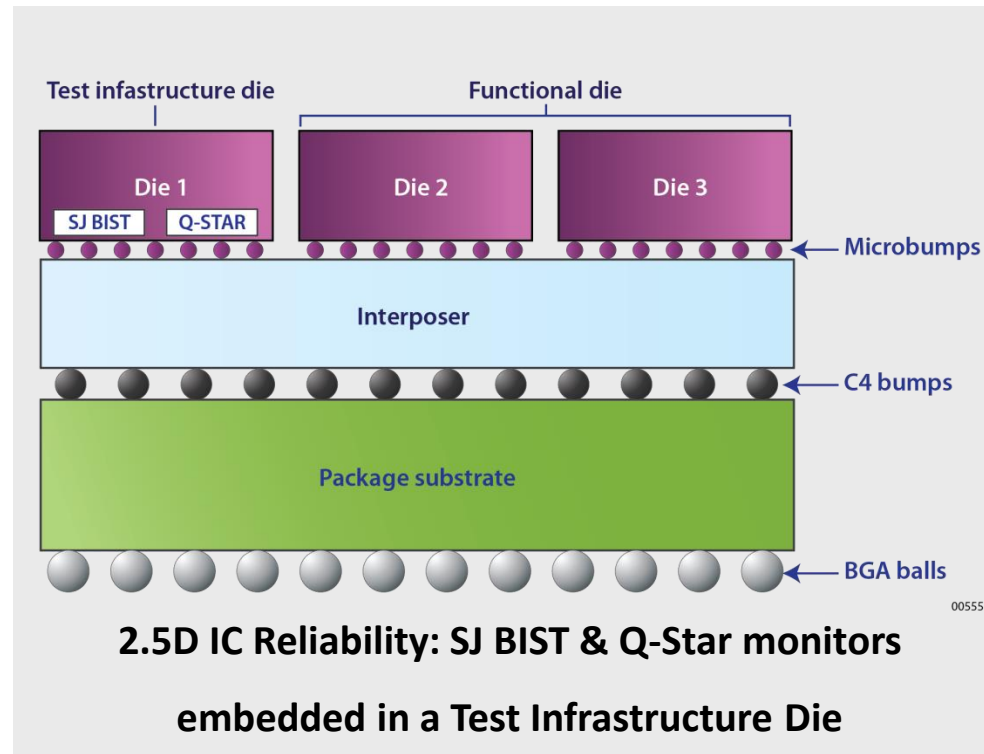
# SJ BIST Application

## Testing Die to Board

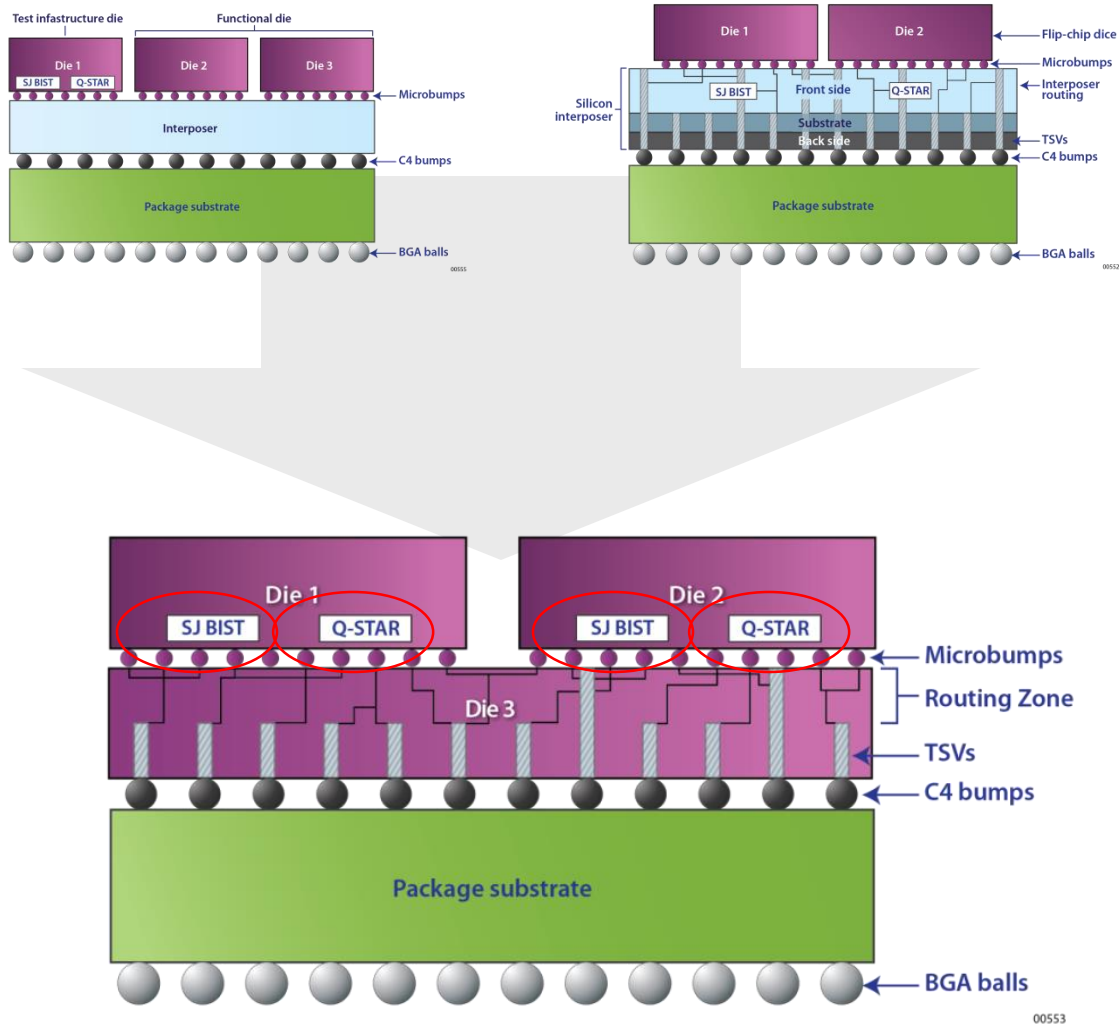


# 2.5D IC Reliability: Test Infrastructure Die

- “Test Infrastructure” die: Connects to strategic traces routed through the interposer
  - Most critical functionality
  - Most sensitive to degradation (e.g., corners or centers of Die 2 or Die 3)
  - Can monitor many signals
- SJ BIST/Q-Star IP embedded in Test Infrastructure die
- Advantages
  - Minimizes interposer overhead
  - Low cost IC
  - Upgrades are simple
- Disadvantages
  - Extra interposer real estate
  - Distance from some signals

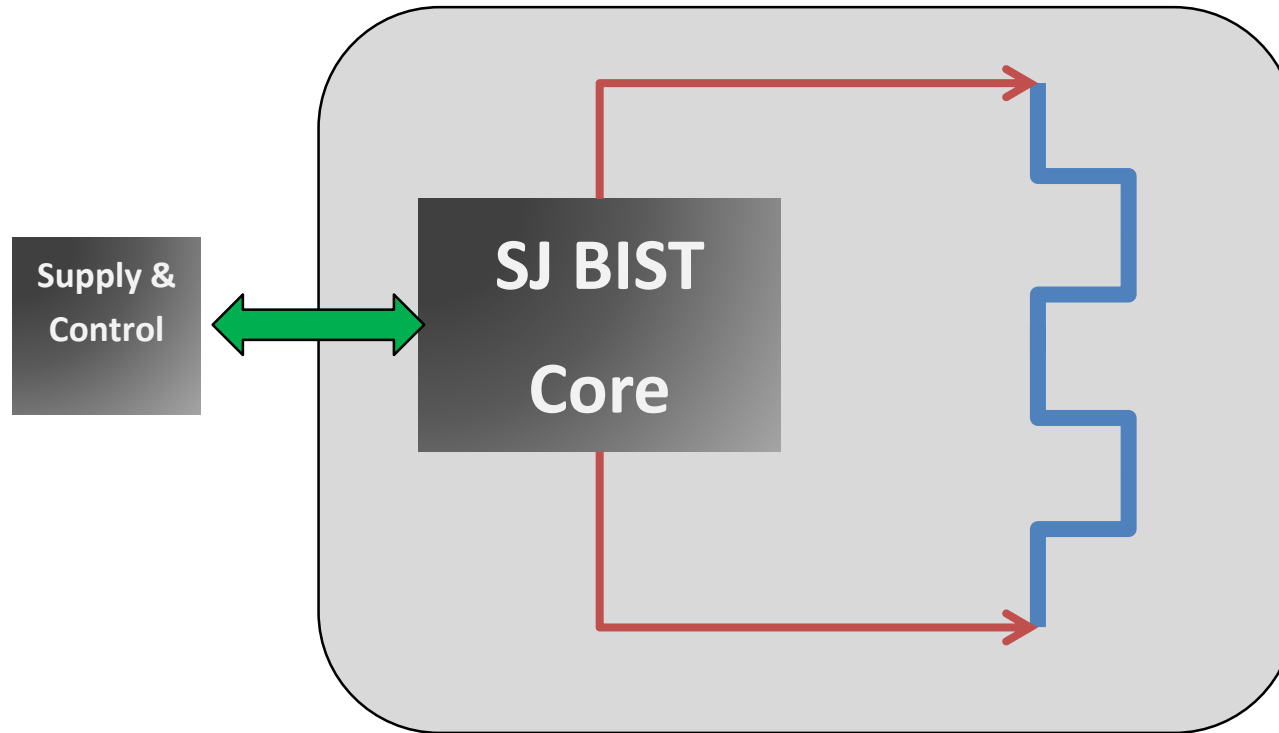


# From 2.5D IC to 3D IC Reliability Monitoring



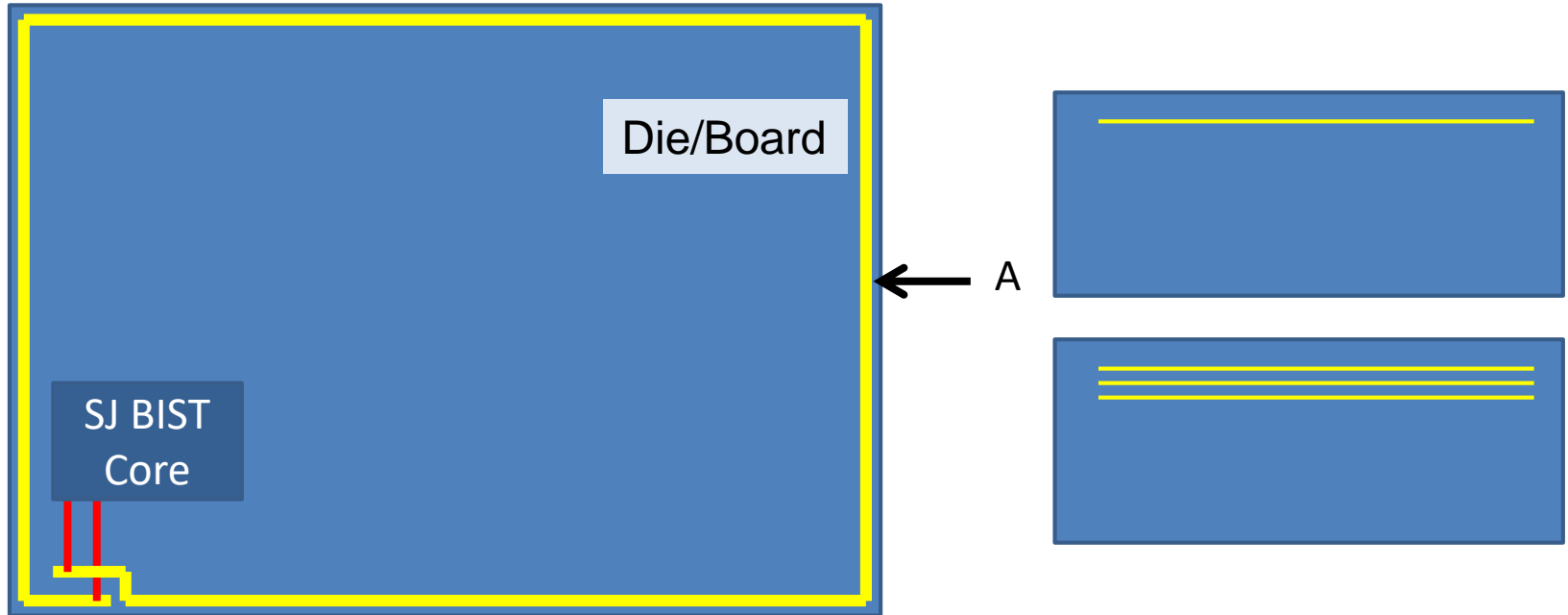
- 3D IC migration: Embed SJ BIST / PGMon IP in TSV-enabled ICs
- Required when no interposer present  
Highest quality monitoring
- Reduces cost and overhead
- Standardized approach for broadest applicability

# Die Crack Detection - Option A



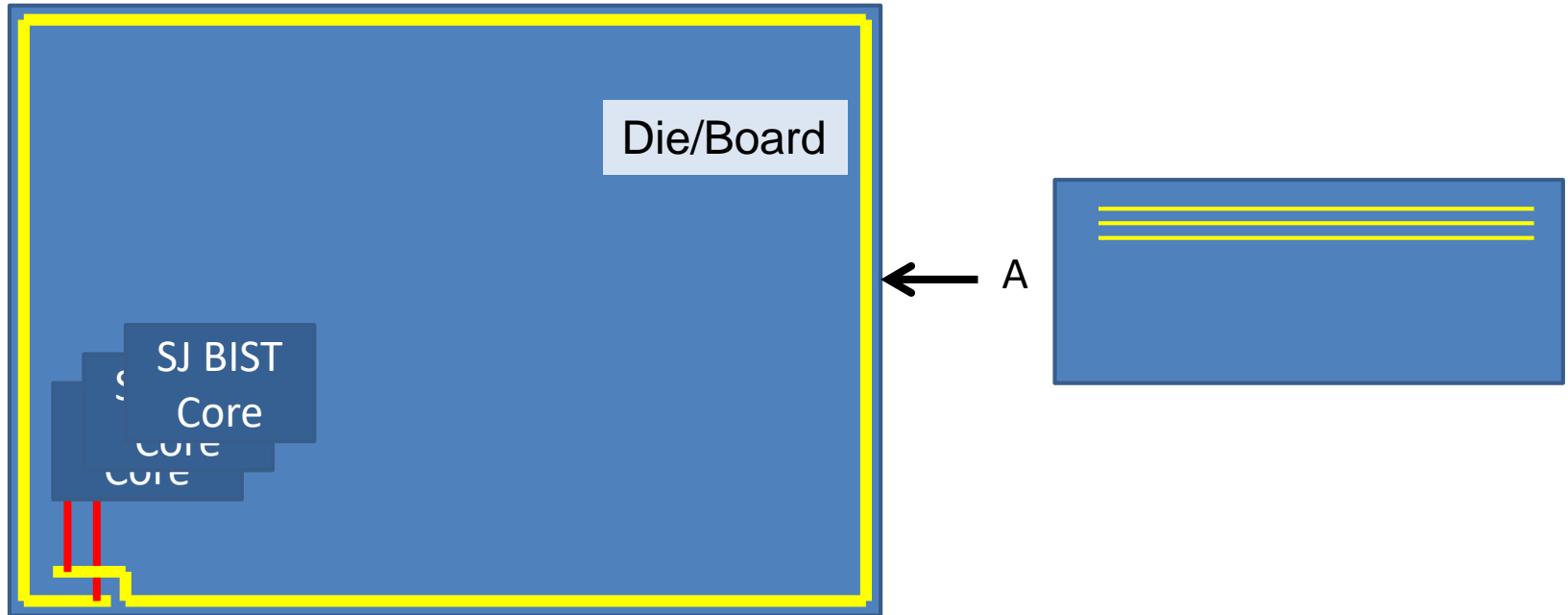
- Test structure & monitor are part of the same die

# Die/Board Crack Detection - Simple Ring Structure



Structure runs on the edge of the die or board and could either be a single layer or a multilayer structure observed by a single SJ BIST core

# Die/Board Crack Detection - Simple Ring Structure – 2

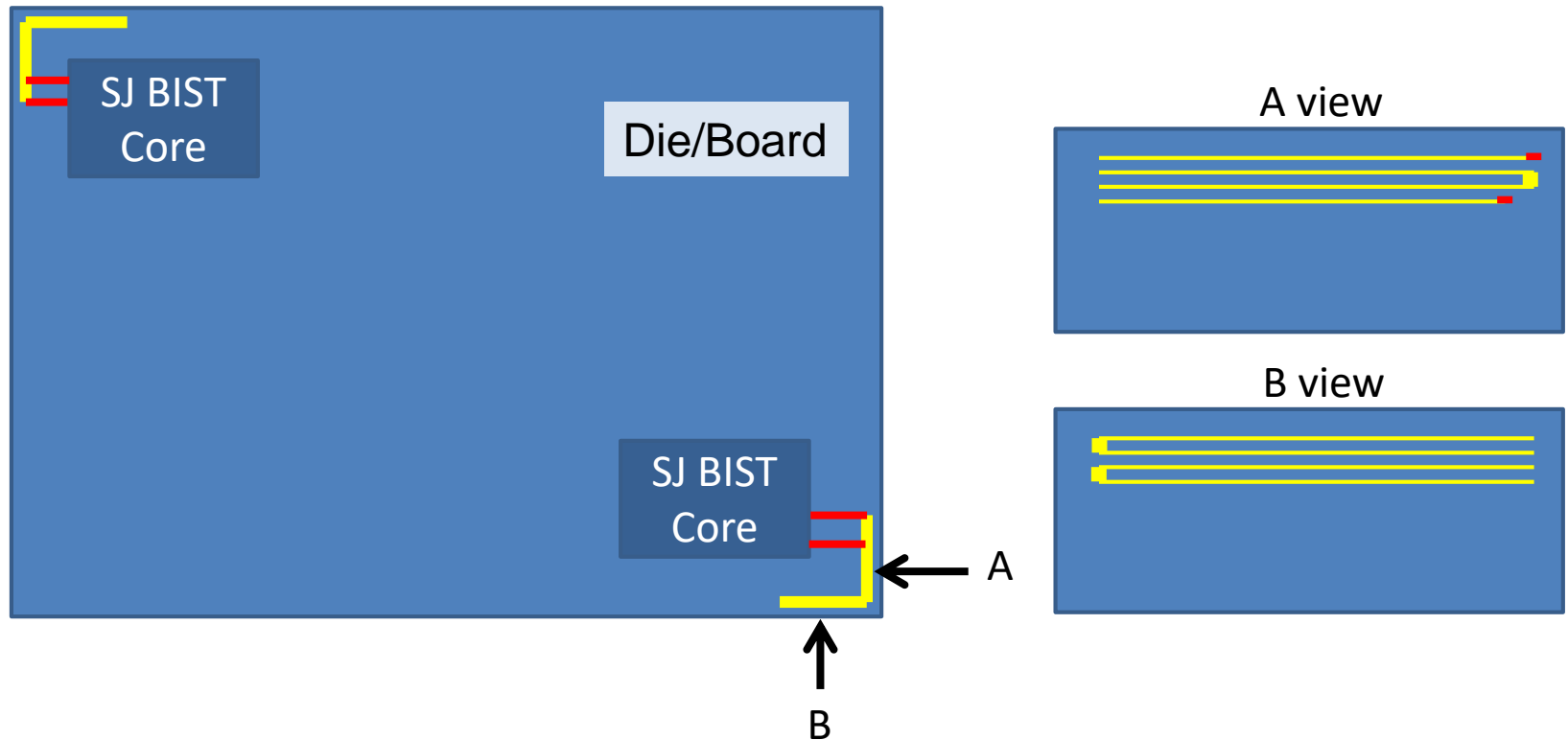


**Multi-Layer Structure runs on the edge of the die or board**

**Each layer is observed by a specific SJ BIST core**



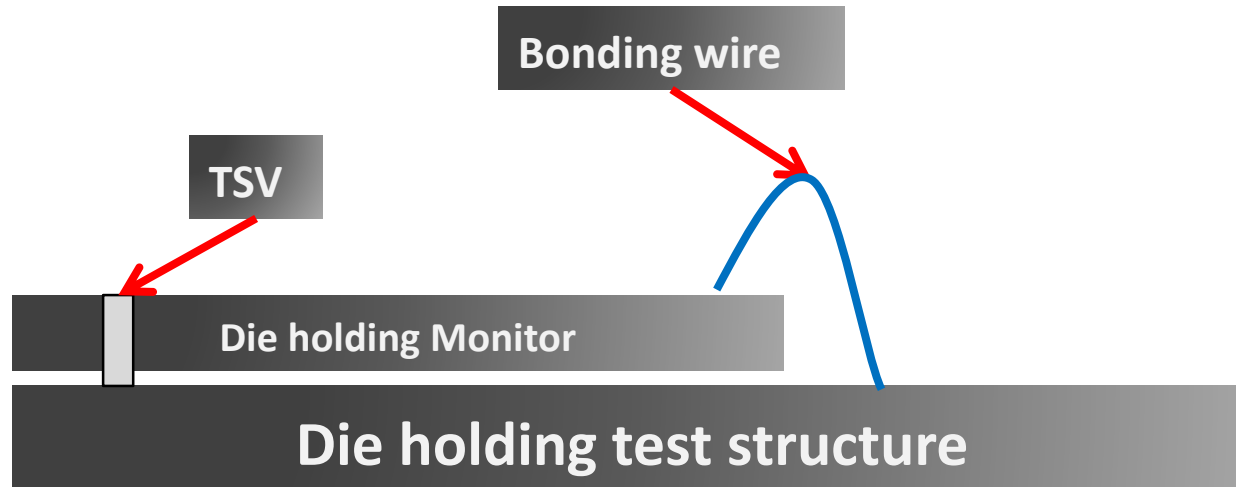
# Die/board Crack Detection - Corner Structure



**Multi-Layer Structure linked to the corners of the die or board**

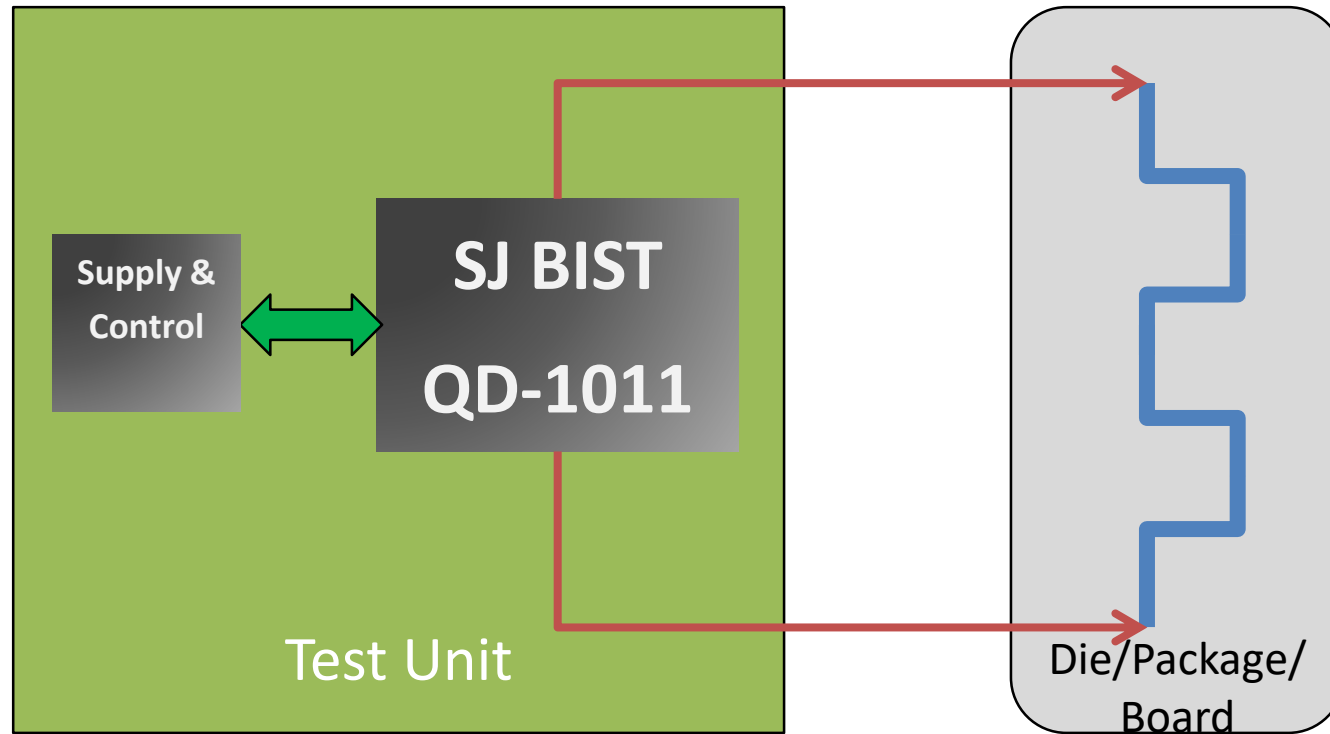
**Each structure is multilayer and is observed by a specific SJ BIST core**

# Die Crack Detection - Option B



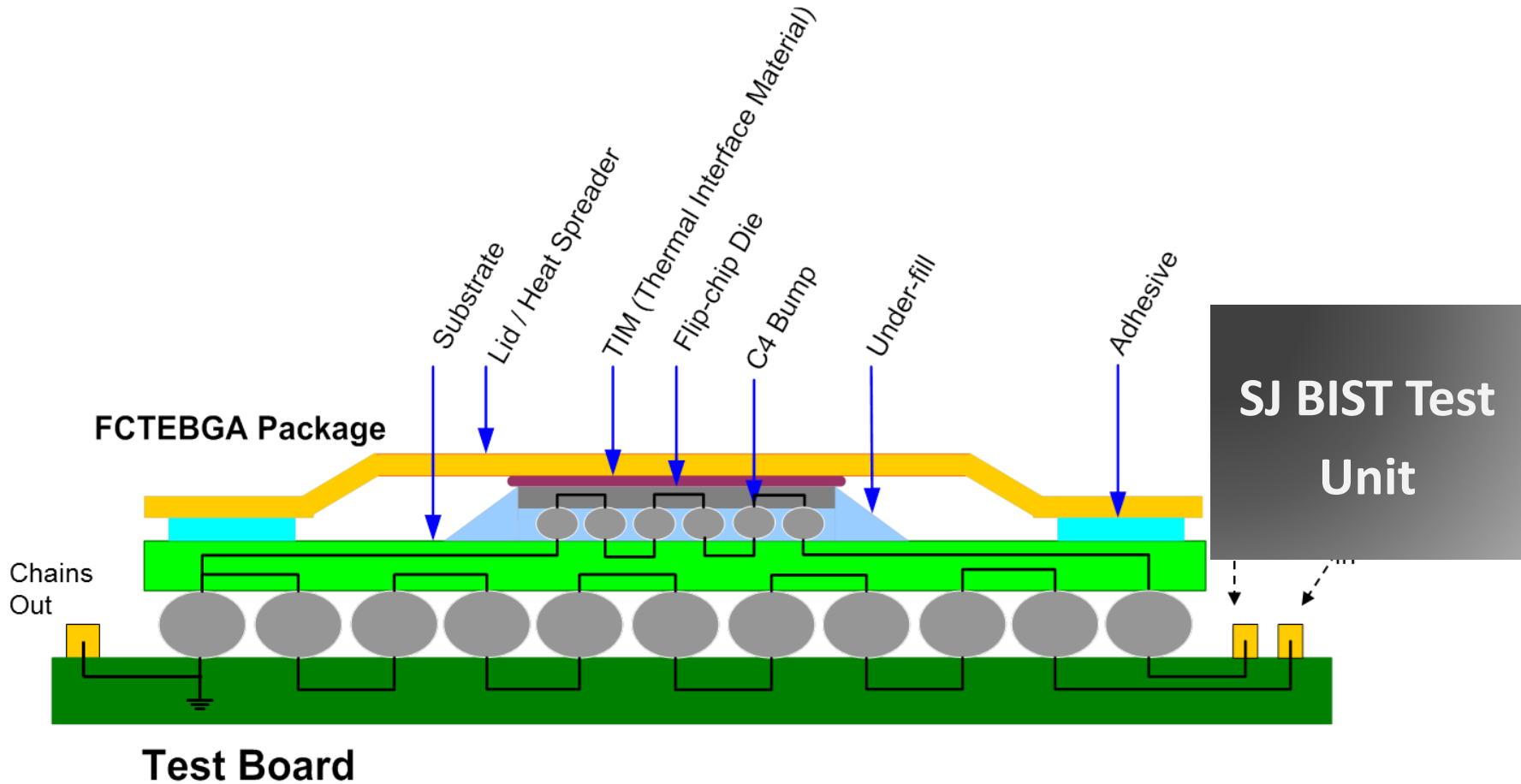
- Test Structure & monitor are on separate dies

# Crack Detection - Option C

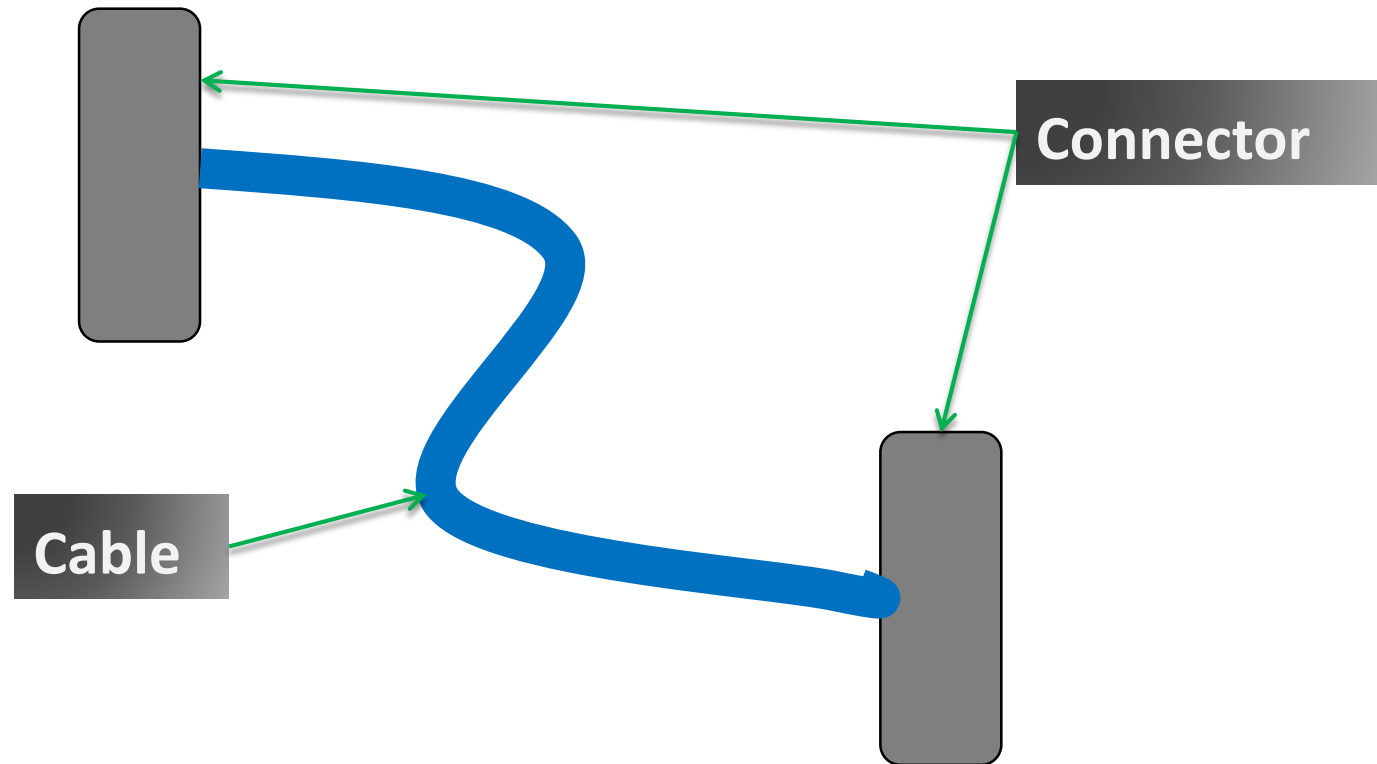


- Test structure and external test equipment

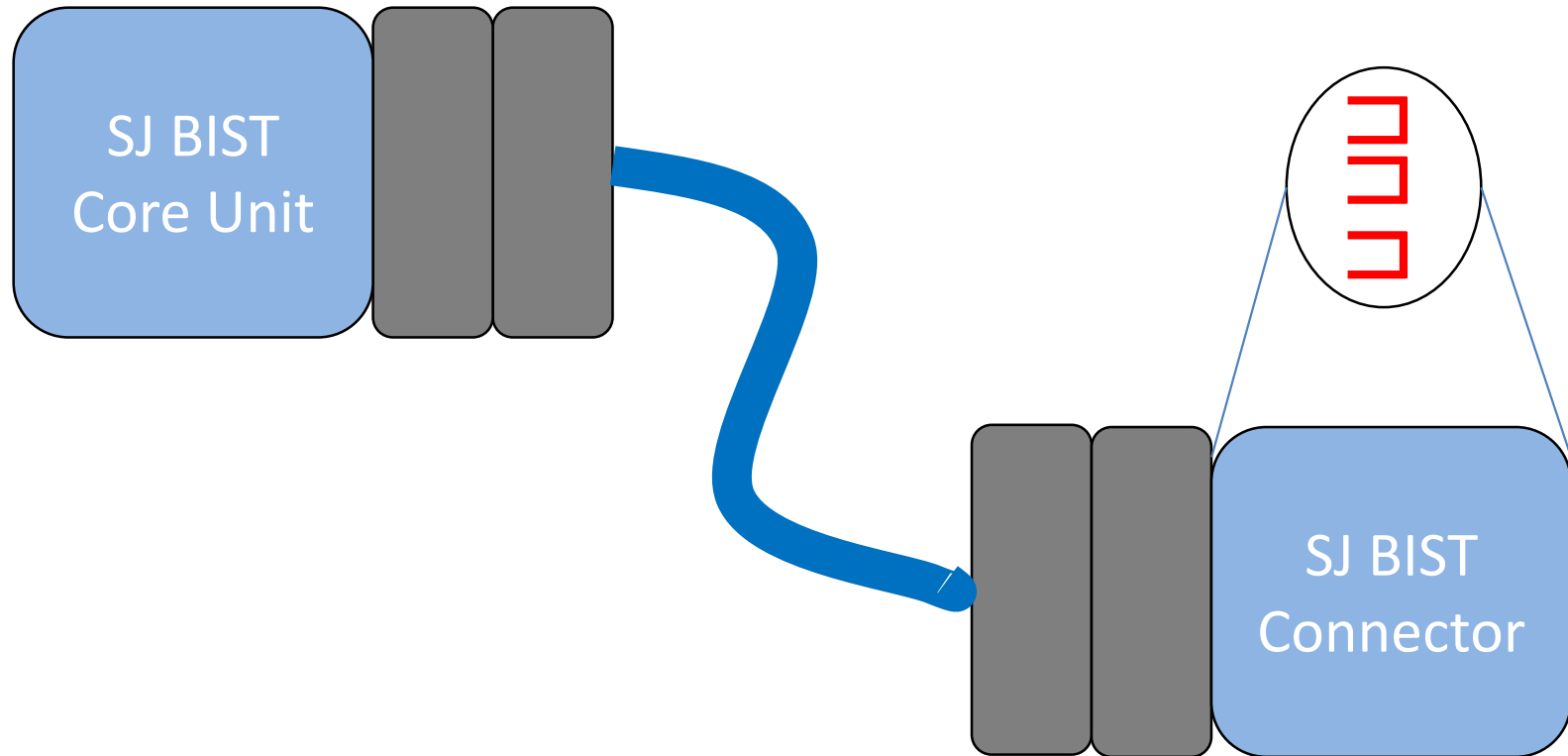
# Daisy Chain Revisited



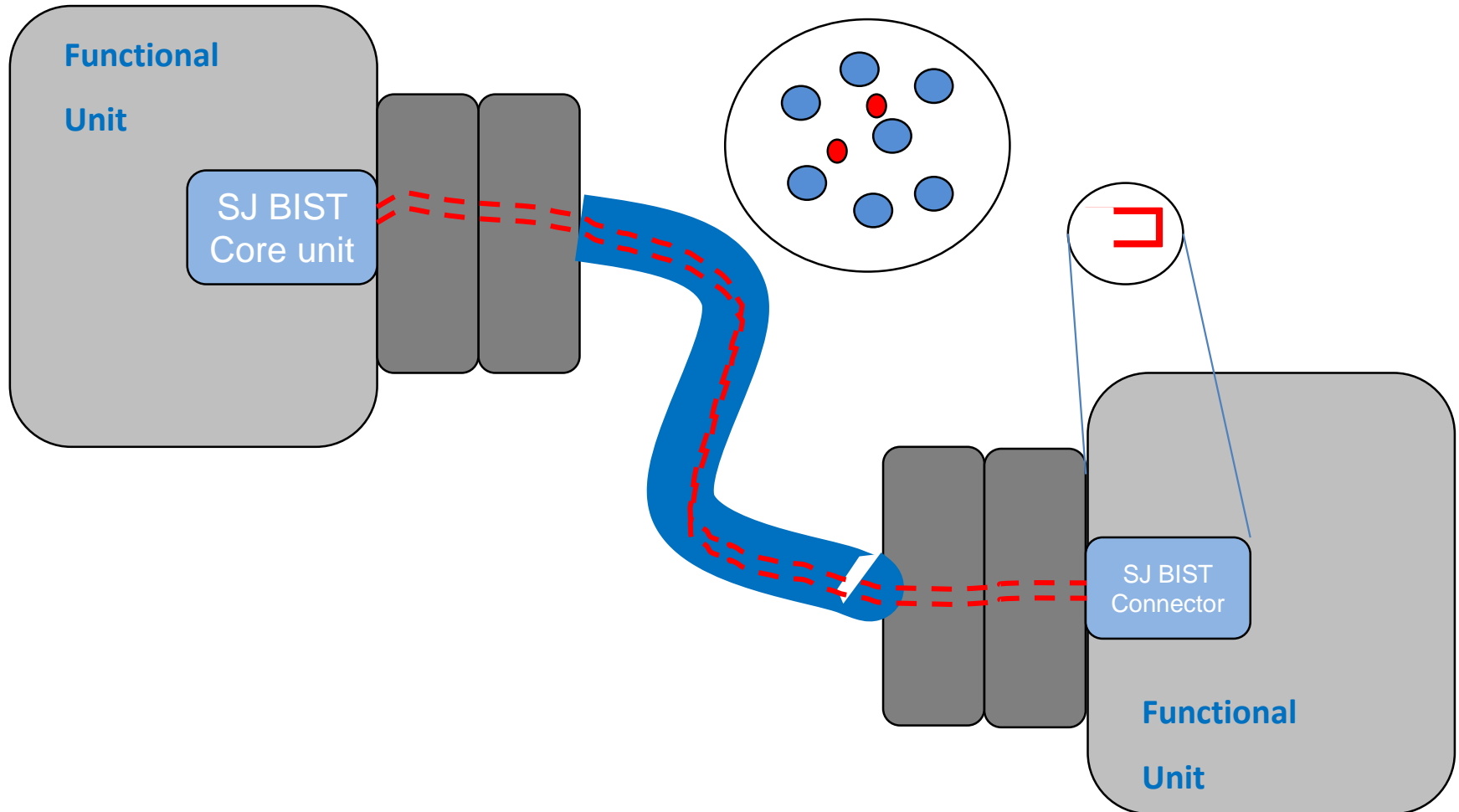
# Testing Cables



# Testing Cables



# Monitoring Cables



# SJ BIST Demonstration/Evaluation Kit





# Interconnect ePHM - Application Case

## ■ Customer

- BAE Systems, Johnson City, NY.

## ■ Problem

- Issue of missions failure due to early FPGA failure.
- Solder joints of BGA packages experience thermo-mechanical stresses causing accumulative fatigue damage.
- Fatigue damage results in spikes of high resistance of increasing frequency and duration as the damage increases.
- The high resistances cause intermittent incorrect levels of signals – as a result, a logical 0 or 1 can be incorrectly set or reset.

## ■ Solution

- Sentinel Interconnect HALT based on deploying SJ BIST during HALT testing of problem board, serving early detection of manufacturing issues and to qualify electronic boards for military-aerospace use

# Interconnect ePHM - Application Case

- **Customer**

- ST Microelectronics – Dallas, TX

- **Problem**

- Package qualification
- Limited timing resolution of event detection units

- **Solution**

- Configurable SJ BIST Solution
- Considerably improved detection capabilities of short term intermittences (events) as well as increased resolution of determining degradation resistance.

# Summary

- SJ BIST
  - Flexible and versatile tool for Interconnect monitoring at time zero and during product lifetime
  - Small core (about 100 eq gates)



# Thank you!

## **Ridgetop Europe nv**

Hans Manhaeve

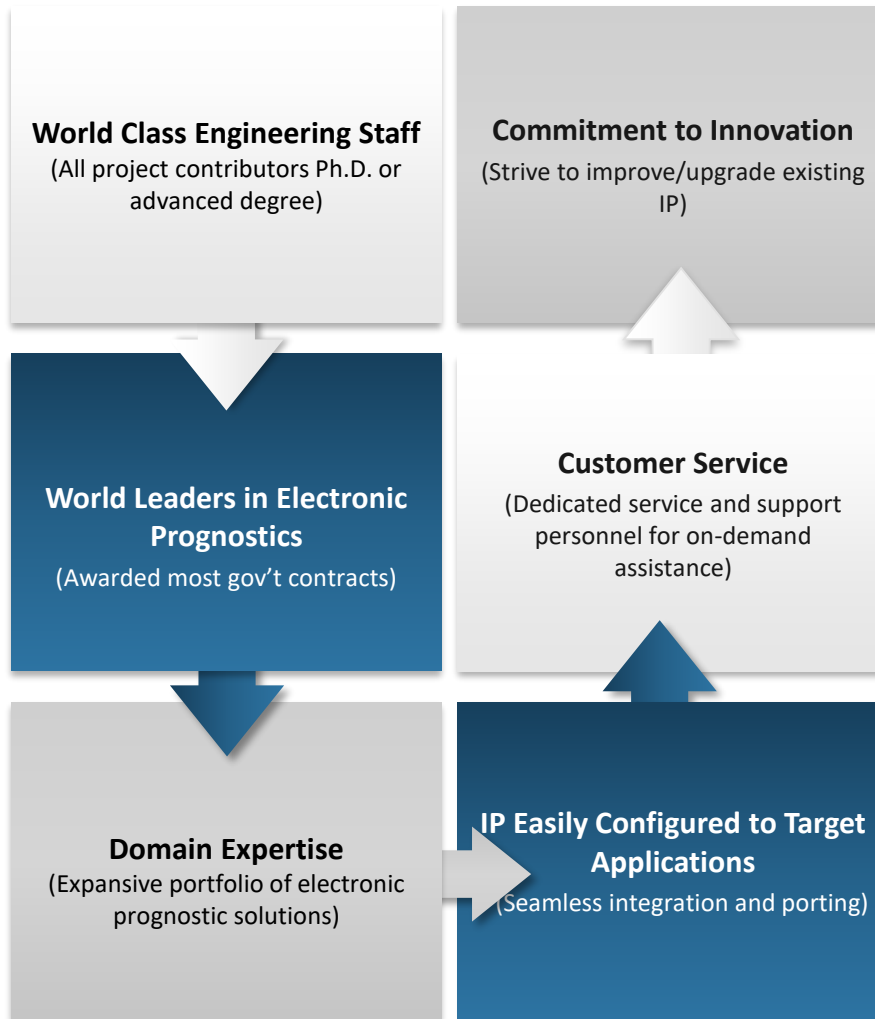
CEO/CTO

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# Ridgetop Delivers



# About Ridgetop

- Ridgetop Europe (formerly Q-Star Test) with HQ in Brugge, Belgium
- Ridgetop Group with HQ in Tucson, AZ.
- Microelectronic Design and Test Solutions:
  - SJ BIST™ Based Test Solutions
  - ProChek™ Semiconductor Characterization System
  - Q-Star Test™ Precision Current Measurement Instruments
  - PDKChek™ In-Situ Test Structures
  - ISO:9001/AS9100C-compliant Design and Integration Services
- Strong market position with commercial and government customers in USA, Canada, Europe, and Asia



Ridgetop Group Facilities in Tucson, AZ



Ridgetop Europe Facilities in Brugge, Belgium